DEMO POSITION2GO

XENSIV™ 24 GHz radar demo board

Board version V1.2

About this document

Scope and purpose

This application note describes the key features of Infineon's DEMO POSITION2GO board equipped with the XENSIV™ 24 GHz BGT24MTR12 MMIC and the 32-bit Arm® Cortex®-M4 based XMC4700 microcontroller and helps the user to quickly get started with the demonstration board.

1. The application note describes the hardware configuration and specifications of the sensor module in detail.
2. It also provides a guide to configure the hardware and implement simple radar applications with the firmware/software developed.

Intended audience

The intended audience for this document are design engineers, technicians, and developers of electronic systems, working with Infineon's XENSIV™ 24 GHz radar sensors for target position estimation using the Frequency Modulated Continuous Wave (FMCW) radar technique.

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1 Introduction

The DEMO POSITION2GO is a demonstration board for Infineon's silicon-germanium (SiGe) based 24 GHz BGT24MTR12 radar chipset. The board is capable of measuring distance, speed, direction of movement and Angle of Arrival (AoA). These features of the board make it suitable for various applications such as tracking humans, presence detection, collision avoidance, etc.

The main radar technique used on the board is FMCW. In this technique, the time delay between the transmitted and received chirp is used for measuring distance to the target(s). The transmitted and received signals are mixed and then quantized for further processing. Multiple chirps (up to 16) are processed in order to create a 2D range-Doppler map to estimate the distance and the velocity of the target(s). Since the MMIC has two receivers, a phase monopulse comparison technique is used to determine the AoA.

The module provides a complete radar system evaluation board including demonstration software and a graphical user interface (GUI) that can be used to display and analyze acquired data in time and frequency domain. An onboard breakable debugger with a licensed firmware from SEGGER enables easy debugging over USB. Infineon's powerful, free-of-charge toolchain DAVE™ can be used to program the XMC4700 microcontroller. The board also features integrated micro-strip patch antennas on the PCB, including the design data, thereby eliminating antenna design complexity at the user end.

This application note describes the key features and hardware configuration of the Position2Go demo board in detail.

1.1 Key features

The primary features of the Position2Go demo board are as follows:

- Detect and track position of multiple targets in outdoor environments
- Measure distance of multiple targets in a user-configurable range (1 to 50 m)
- Detect motion, presence, speed and direction of movement (approaching or retreating) for human targets
- Small form factor: 5 x 4.5 cm
- Operational in different weather conditions such as rain, fog, etc.
- Can be hidden in the end application as it detects through non-metallic materials
- Dual analog amplifier stages for each RX channel with user-configurable gain settings
- Micro-strip patch antennas with 12 dBi gain and 19 x 76 degrees Field of View (FoV)
- Onboard PMOS switch for duty-cycle operation and low power consumption

Note: The platform serves as a demonstrator platform with the software to perform simple motion sensing, ranging and tracking. The test data in this document show typical performance of Infineon-produced platforms. However, board performance may vary depending on the PCB manufacturer and specific design rules they may impose and components they may use.

1.2 Overview

The Position2Go demo board consists of the following key components:

- BGT24MTR12 – highly integrated 24 GHz transceiver MMIC with one transmitter (TX) and two receivers (RX)
- XMC4700 – 32-bit Arm® Cortex®-M4 based microcontroller for signal processing
- IRLHS2242 – 20 V single P-channel HEXFET power MOSFET for duty-cycle operation
- XMC4200 onboard debugger – licensed firmware for Serial Wire Debug (SWD) and UART to USB communication

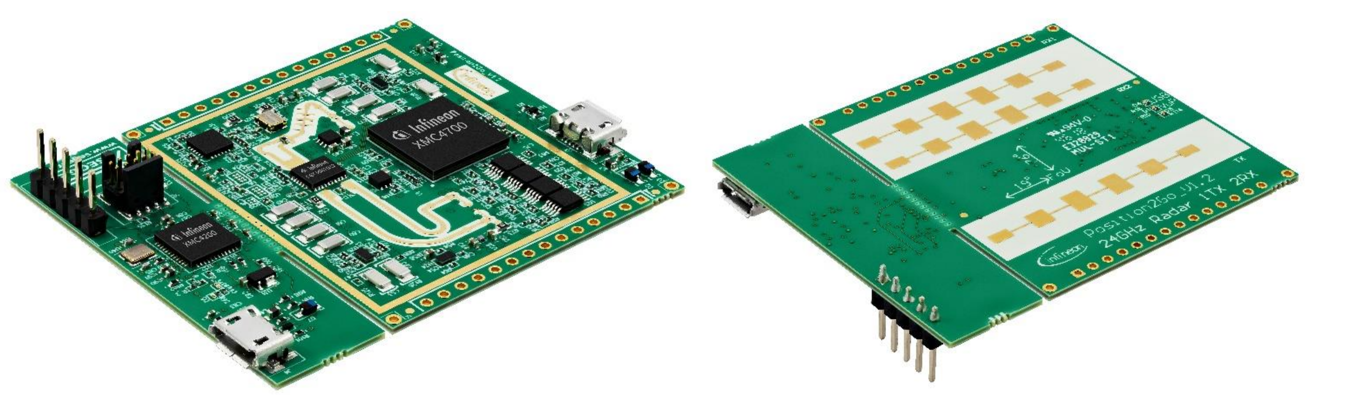


Figure 1 Position2Go demo board

2 System specifications

Table 1 gives the specification of the Position2Go radar system.

Table 1 Position2Go demo board specifications

Parameter	Unit	Min.	Typ.	Max.	Comments
System performance					
Detection speed	km/h	0.7		22.4	Based on the formula: • Min. speed (m/s) = λ /(2 × $N_{FFT,D}$ × PRT) • Max. speed (m/s) = λ /(4 × PRT) in P2G_FMCW firmware, where: λ = wavelength (m) $N_{FFT,D}$ = DOPPLER_FFT_SIZE PRT = Pulse Repetition Time
Detection distance	m	0.6		15	Radar Cross-Section (RCS) = 1 m^2 Max. distance is based on 100 LSB range detection threshold
Range accuracy (for values > 0.6 m)	m		±0.2		RCS = 1 m^2
Range resolution	m		0.9		With Blackman window (BW 200 MHz, 300 µs ramp up, 64 samples/chirp, 256 FFT size)
Angle accuracy	Degrees		≤ 5		FoV +/-30 degrees RCS = 1 m^2 at 3 m range
	Degrees		≤ 10		FoV +/-65 degrees RCS = 1 m^2 at 3 m range
Power supply					
Supply voltage	V	3.3	5	5.5	
Supply current	mA		420		All blocks on (no duty-cycle)
Transmitter characteristics					
Transmitter frequency	GHz	24.0		24.25	
Effective Isotropic Radiated Power (EIRP)	dBm		18		EIRP controllable via SPI for ISM operation
System phase noise with PLL	dBc/Hz		-89		At 100 kHz offset, VCOARSE = VFINE. Measured in CW mode
External oscillator frequency	MHz		40		
Receiver characteristics					
Receiver frequency	GHz	24.0		24.25	
IF conversion gain – (stage 1)	dB		23.5		
-3dB bandwidth (stage 1)	kHz		14 to 140		Can be selected by reconfiguring the ADC pins in DAVE™ project

Parameter	Unit	Min.	Typ.	Max.	Comments
IF conversion gain (stage 1 + stage 2)	dB	23.5	47.5	65.5	Configurable by PGA SPI settings of stage 2
-3 dB bandwidth – (stage 1 + stage 2)	kHz		13 to 105		Default setting of the sensor module when delivered
Antenna characteristics (measured)					
Antenna type (TX/RX)			1 x 6		
Horizontal – 3dB beamwidth	Degrees		76		
Elevation – 3dB beamwidth	Degrees		19		
Horizontal sidelobe level suppression	dB		20		
Vertical sidelobe level suppression	dB		20		

Note: *The above specifications are indicative values based on typical datasheet parameters of BGT24MTR12 and simulation of several other parameters (antenna characteristics and baseband section) and can vary from module to module. The numbers above are not guaranteed indicators for module performance for all operating conditions.*

3 Hardware description

This section presents a detailed overview of the Position2Go demo board hardware specifications, including the MMIC considerations, power supply and board interfaces.

3.1 Overview

The Position2Go demo board contains a radar main board and a breakable debugger board, shown in Figure 2. The radar main board contains the following sections:

- RF part – consists of the Infineon 24 GHz radar MMIC – BGT24MTR12 and the tapered micro-strip patch antennas for the TX and RX sections.
- Analog amplifier part – provides the interface between the RF and digital parts of the board. It has programmable gain amplifiers (PGAs), which can be programmed over the SPI to provide variable gains for different use cases.
- Frequency control part – contains a low-noise fractional-N PLL.
- Digital part – consists of a XMC4700, 32-bit Arm® Cortex®-M4 microcontroller from Infineon to sample and process the analog data from the radar front end and also to configure the BGT24MTR12, PLL and PGAs via an SPI.

The board demonstrates the features of the BGT24MTR12 RF front-end chip and gives the user a complete “plug and play” radar solution. It makes it possible to quickly gather sampled radar data that can be used to develop radar signal-processing algorithms on a PC or implement target detection algorithms directly on the microcontroller using DAVE™.

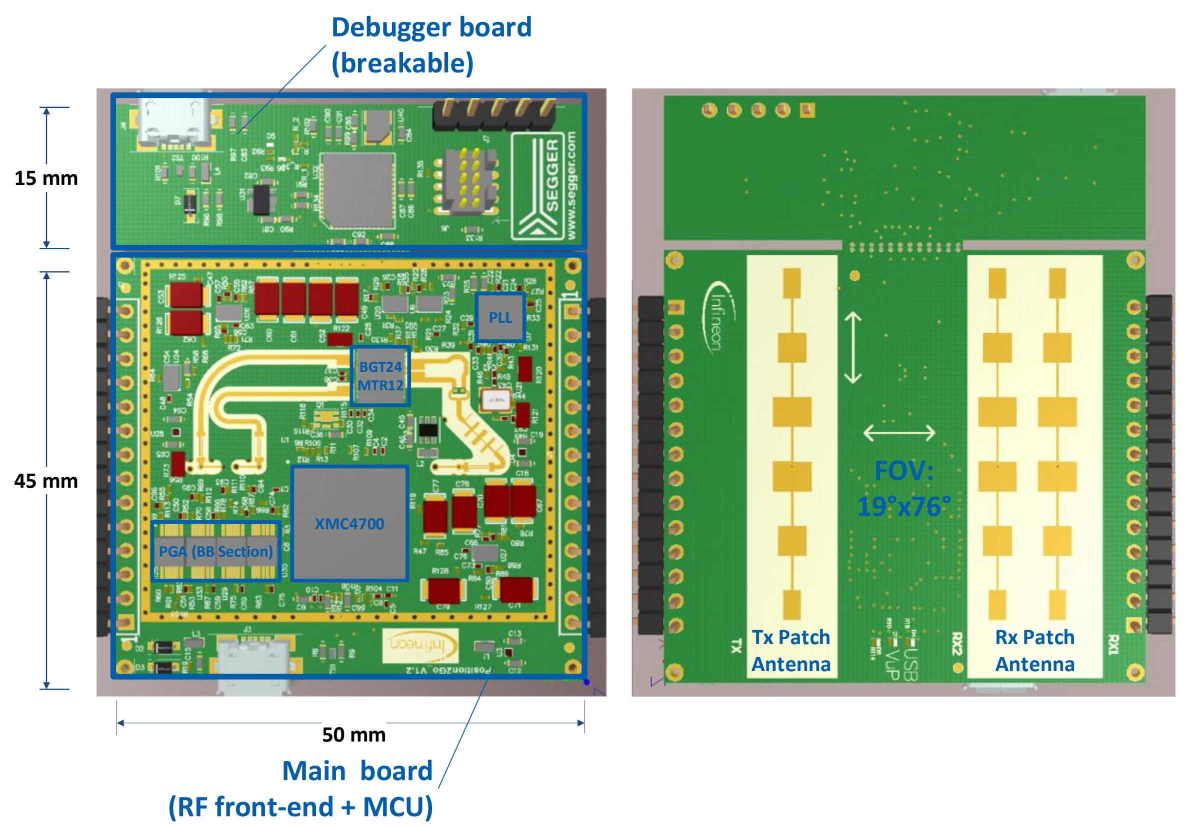


Figure 2 **Position2Go demo board main components and dimensions**

The Position2Go demo board has the following hardware features:

- BGT24MTR12 24 GHz RF front-end chip with 1 TX and 2 RX with the following specification:
  - Low Noise Figure (NFSSB): 12 dB
  - High conversion gain: 26 dB
  - High 1 dB input compression point: -12 dBm
  - Switchable prescaler with 1.5 GHz and 23 kHz output
  - On-chip power and temperature sensors
- XMC4700 Cortex-M4 microcontroller for sampling and signal processing of the analog signals with the following features:
  - 144 MHz CPU frequency, 2048 kB Flash and 352 kB RAM size
  - Four Capture and Compare Units (CCU4) for use as general-purpose timers
  - Four 12-bit ADCs, 26 channels each with input out-of-range comparators, and a 12-bit DAC with two channels
  - USB 2.0 device, with integrated PHY, Controller Area Network interface (MultiCAN), Full-CAN/Basic-CAN with six nodes, 256 message objects (MOs), data rate up to 1 MBaud
  - Six Universal Serial Interface Channels (USICs), providing six serial channels, usable as UART, double-SPI, quad-SPI, I2C, I2S and LIN interfaces
- Onboard breakable debugger with UART communication
- Onboard low-noise fractional-N PLL with chirp generation
- Dual analog amplifier stage for each RX channel with programmable gain settings
- Micro-strip patch antennas with 12 dBi gain (simulated) and 19 x 76 degrees FoV
- Onboard PMOS switch for duty-cycle operation of BGT24MTR12
- Power supply:
  - Via micro-USB connector
  - Via external power supply (5 V maximum)

3.2 Block diagram

Figure 3 shows the block diagram of the demo board. The board is split into a main RF unit and a breakable debugger unit for programming. The RF unit consists of the highly integrated 24 GHz transceiver MMIC BGT24MTR12 with 1 TX and 2 RX. The MMIC features an integrated Voltage Controlled Oscillator (VCO), Power Amplifier (PA), integrated temperature and power sensors, prescalers and IQ receivers.

The board also has integrated micro-strip patch antennas, and a Wilkinson combiner is used to combine the differential transmitter output power from the radar MMIC before feeding it to the antennas. Each receiver channel is connected to a dual analog amplifier stage at its IF outputs. A 32-bit Arm® Cortex®-M4 XMC4700 microcontroller is used to sample and process the analog down-converted signals from the baseband amplifiers using the integrated 12-bit ADC, and also control the radar chip via the SPI interface. The output power of the radar chip and the gain of its receive section can be controlled via the SPI settings. There are also SPI commands to read out the different sensor outputs.

A low-noise fractional-N Phase Locked Loop (PLL) IC is used to perform the frequency control and ramp generation. The output of the /16 prescaler on the radar MMIC is connected to the PLL's RF input pins and the output voltage from the PLL's charge pump is connected via a loop filter to the tuning ports of the BGT24MTR12, thereby forming a closed-loop system. This procedure is used to lock the transmitted signal of the module to an output frequency inside the ISM band. The /65536 prescaler produces a low-frequency output signal (23 kHz), which is connected to a CCU4 of the XMC4700 for monitoring purposes.

The module is powered over the micro-USB plug, and several low-noise voltage regulators are used to provide a regulated power supply to the different building blocks .The BGT24MTR12 MMIC is supplied over a PMOS switch, which enables operation of the sensor in a duty-cycle mode. The Position2Go features a breakable onboard debugger, which comes preloaded with licensed firmware for debugging and communicating with the main radar MCU via the UART pins. Pin headers on the PCB enable the sensor module to interface with an external processor.

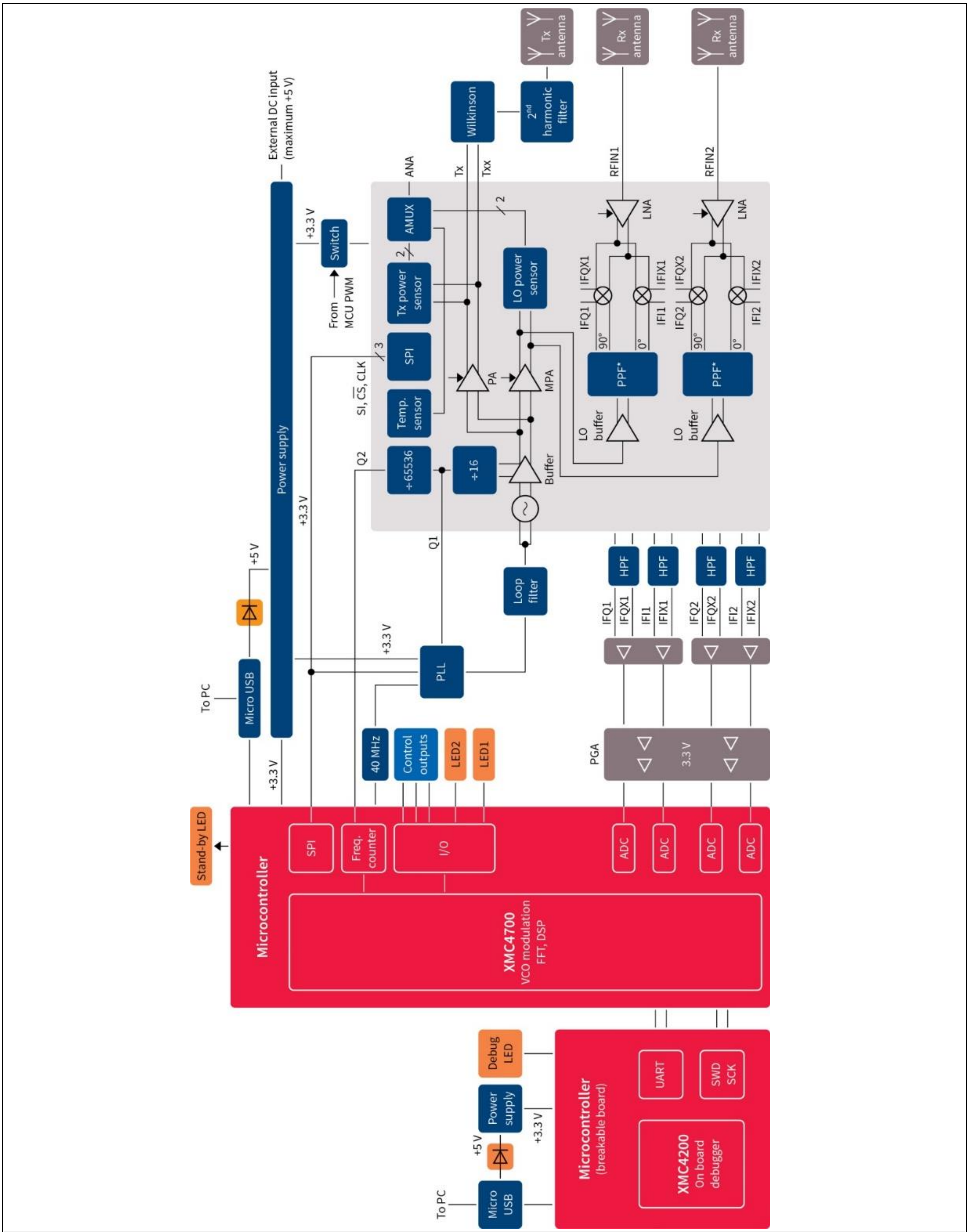


Figure 3 **Position2Go demo board block diagram**

3.3 Power supply

Figure 4 shows the power supply concept used on the module. The board is powered via micro-USB connector when used with a PC. The power supply is via an external DC input pin (5 V maximum). The USB plugs on the main board as well as the breakable debugger board can be used to supply the module

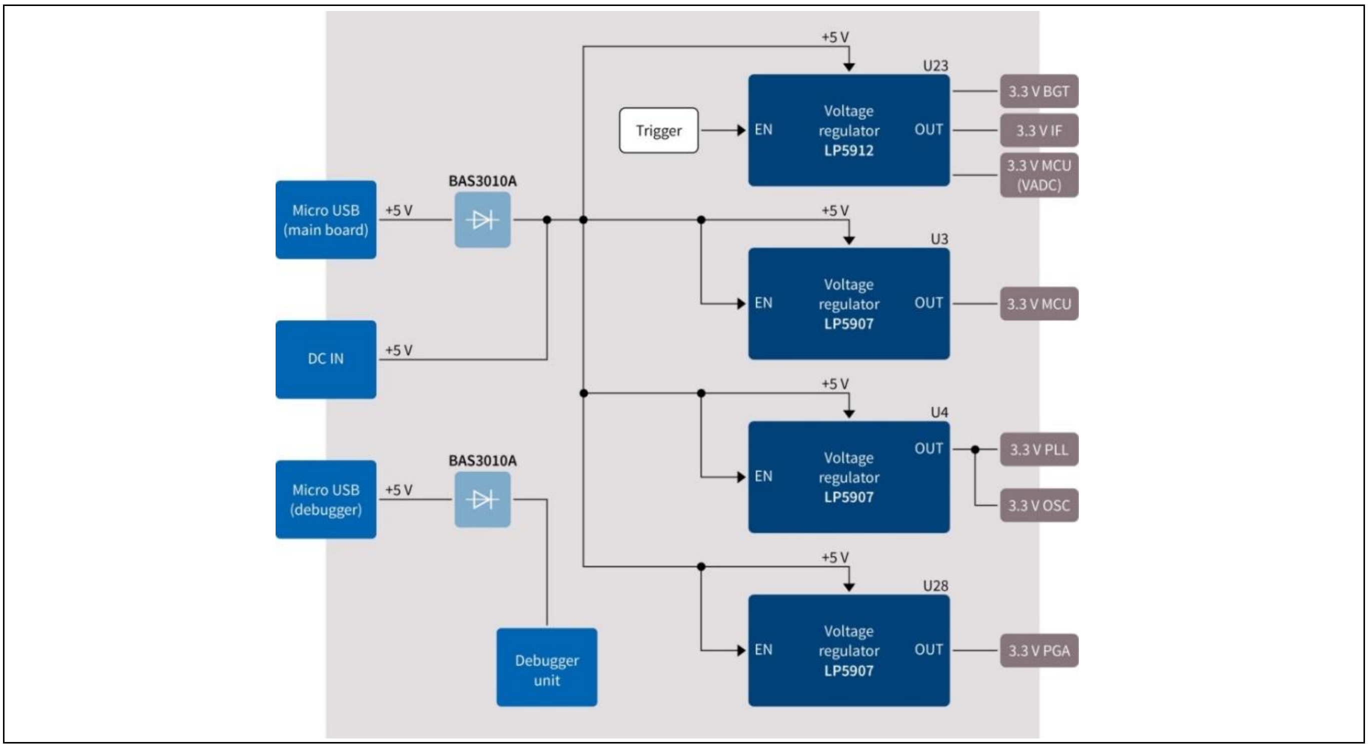


Figure 4 **Power supply block diagram**

The power supply via the USB or external input is provided to four different voltage regulators. The 24 GHz transceiver MMIC is powered by a low-noise voltage regulator U23. U23 has an enable pin that must be triggered via the pin P1.4 of the MCU to enable the LDO. Regulator U20 is also used to supply the analog domain of the XMC4700 MCU and the first baseband IF amplifier stage. A second low-noise voltage regulator U3 is used to supply the digital MCU of the board. U4 is used to power up the PLL and the 40 MHz reference oscillator. The enable pins of U3 and U4 are hardwired to their input voltage pins on the PCB and are not available to the user. Additionally, another low-noise regulator U28 is used to supply the PGA.

3.4 RF front-end

Figure 5 shows the top view of the RF front end. The RF front end can be shielded with a cover and absorber material to get the best RF performance. The following paragraph describes the various sections of the RF front end in detail.

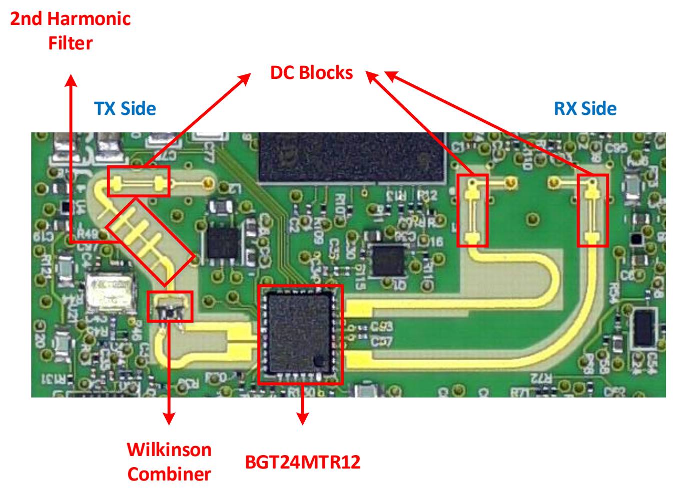


Figure 5 RF front-end top view

3.4.1 Board stack-up

It is necessary to use a defined board layer stack-up for proper functioning of the RF part. All the micro-strip RF parts must be calculated according to the stack-up used. The cross-sectional view of the PCB is shown in Figure 6. The module uses six-layer stack-up with a symmetrical RO-4350B core. The matching structures for the transmitter and receiver parts are designed based on this stack-up.

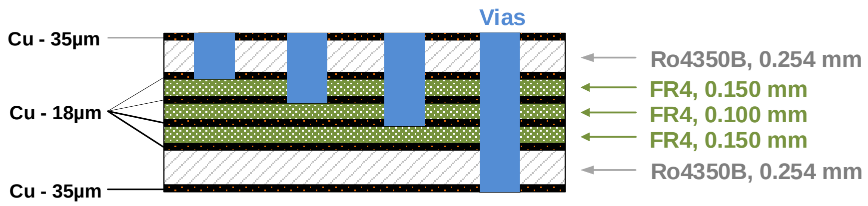


Figure 6 PCB cross-section

The most important part for the RF micro-strip components is the top and bottom RO-4350B, 0.254 mm-thick core. On the top layer (layer 1) are the micro-strip structures, and layer 2 is the RF ground for the micro-strip components used on the top layer. Layer 3 and layer 4 are used for routing various signals. On the bottom layer (layer 6) are the micro-strip patch antennas and layer 5 is the RF ground for the micro-strip patch antennas. The substrate thickness for the other layers have been chosen taking into account the blind-via diameters used on the PCB, and this can vary depending on the PCB manufacturing technology (aspect ratio). From simulations it was observed that such variation of the thickness of these FR4 substrates has a very low impact on the RF performance.

3.4.2 BGT24MTR12 MMIC

The heart of the sensor module is the highly integrated BGT24MTR12 24 GHz transceiver MMIC. Figure 7 shows the detailed block diagram of the MMIC.

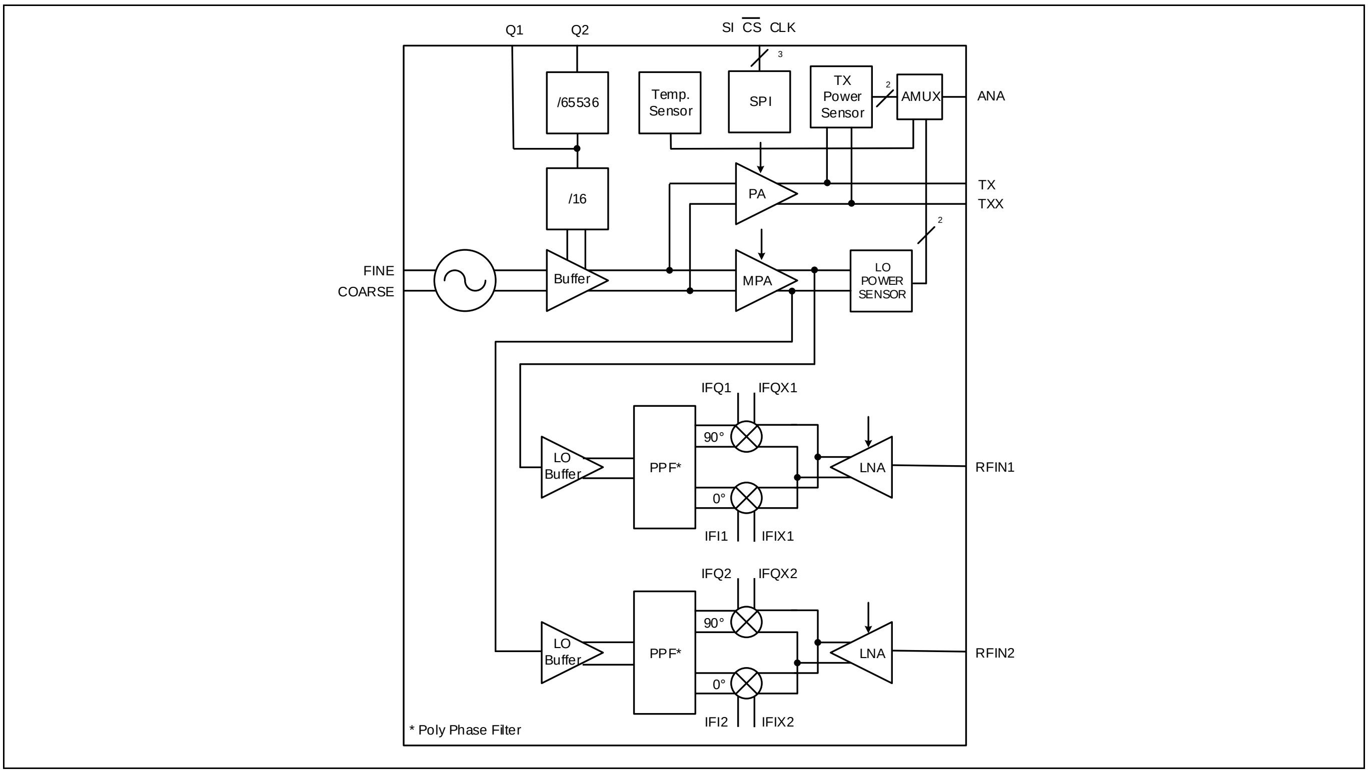


Figure 7 BGT24MTR12 block diagram

The MMIC features a very high level of integration, which includes a VCO with prescaler outputs for frequency control, transmitter chain including amplifiers for both TX and LO outputs, and dual receiver section with Low-Noise Amplifiers (LNAs) and mixers. The dual receive channels help to determine the AoA of the signal from the radar target.

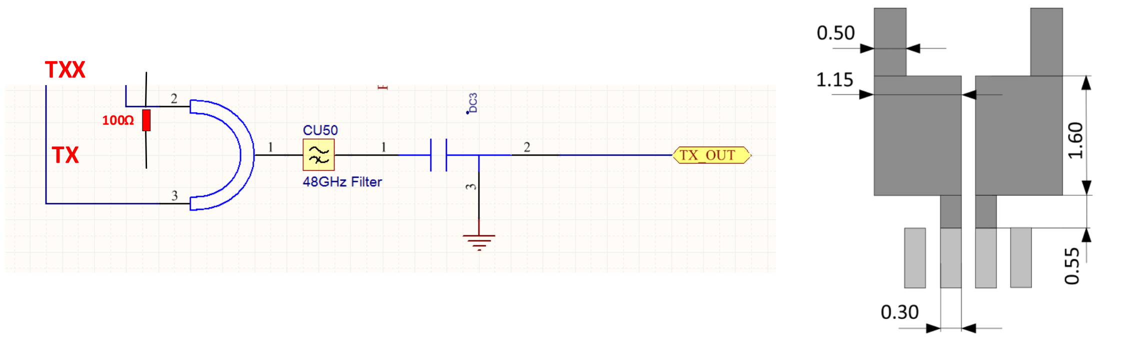
The VCO is a free-running, fundamental oscillator. It can be controlled by two tuning inputs – one for coarse preadjustment, and one for fine-tuning. There are two prescalers available in the VCO section of the chip. The first prescaler has an output frequency of 1.5 GHz and can be used to feed an RF-PLL for frequency control. The second prescaler has a 23 kHz square-wave output that may be used by a microcontroller-based software loop.

The TX section consists of a power amplifier with a differential output. Its typical output power is +11 dBm and can be reduced in eight steps down to 2 dBm. A part of the TX signal is used as the LO signal for the on-chip mixers. The receiver sections have a single-sideband NF of 12 dB and a voltage conversion gain of 26 dB. The gain of the LNA can be reduced by a typical gain-step of 5 dB. The built-in quadrature down-conversion mixers translate the RF signal directly to zero-IF.

Additionally, the chip features power sensors on both TX outputs and LO outputs, as well as a temperature sensor that supports the implementation of a software-based loop to control the VCO. The settings of the different internal building blocks can be controlled via an SPI.

3.4.3 Module transmitter section

The transmitter output of BGT24MTR12 is differential. The differential outputs are first connected over matching structures followed by a Wilkinson power combiner. The matching structures compensate for the bondwire inductance and other parasitic effects due to the VQFN package. Figure 8a shows the schematic of the transmitter section and Figure 8b the dimensions of the matching structures used at the TX outputs. The Wilkinson power combiner combines the differential signals into single-ended ones. Following the power combiner, a second harmonic micro-strip filter is used. The harmonic filter provides an attenuation greater than 20 dB for frequencies around 48 GHz and shows a simulated loss of approximately 0.5 dB. The filter path then goes over a DC block and a feed-through via to the other side of the PCB to the antennas. The simulated loss for the entire RF section connecting the TX output from the MMIC to the antennas on the other side of the board including the vias was approximately 2 dB. There are DC shorts before the feed-through vias for enhanced ESD protection.

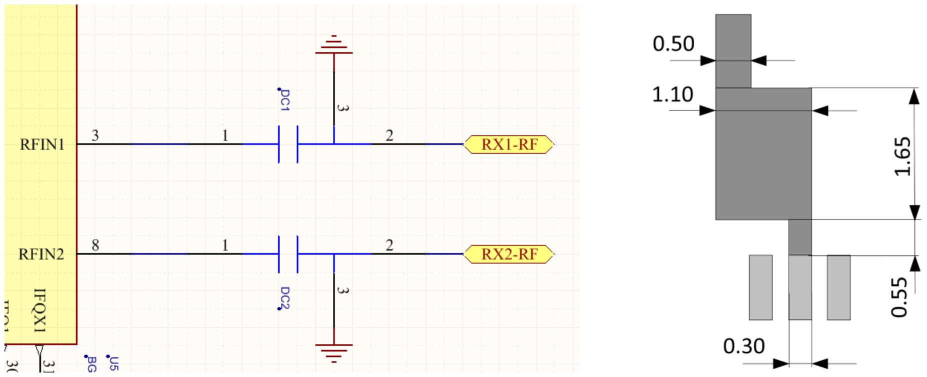


a) Schematic – Transmitter section b) TX matching structure in [mm]

Figure 8 **Transmitter section schematic and matching structure dimensions**

3.4.4 Module receiver section

The receiver input of the BGT24MTR12 is single-ended. The RX input is connected over a matching structure, a DC block and a feed-through via to the antennas on the other side of the board. Figure 9a shows the schematic of the receiver section and Figure 9b the dimensions of the matching structures used at the RX input. The simulated loss for the entire RF section connecting the RX input at the MMIC to the antennas on the other side of the board including the vias was approximately 1 dB. There are DC shorts before the feed-through vias for enhanced ESD protection.



a) Schematic – Receiver section b) RX matching structure in [mm]

Figure 9 **Receiver section schematic and matching structure dimensions**

3.4.5 Antennas

The Position2Go demo board features a 6 x 1 series-fed tapered array antenna for the transceiver and receiver sections. The antenna has a measured gain of 12 dBi (simulated) and an opening angle of 19 x 76 degrees. Figure 10 shows the measured 2D radiation pattern.

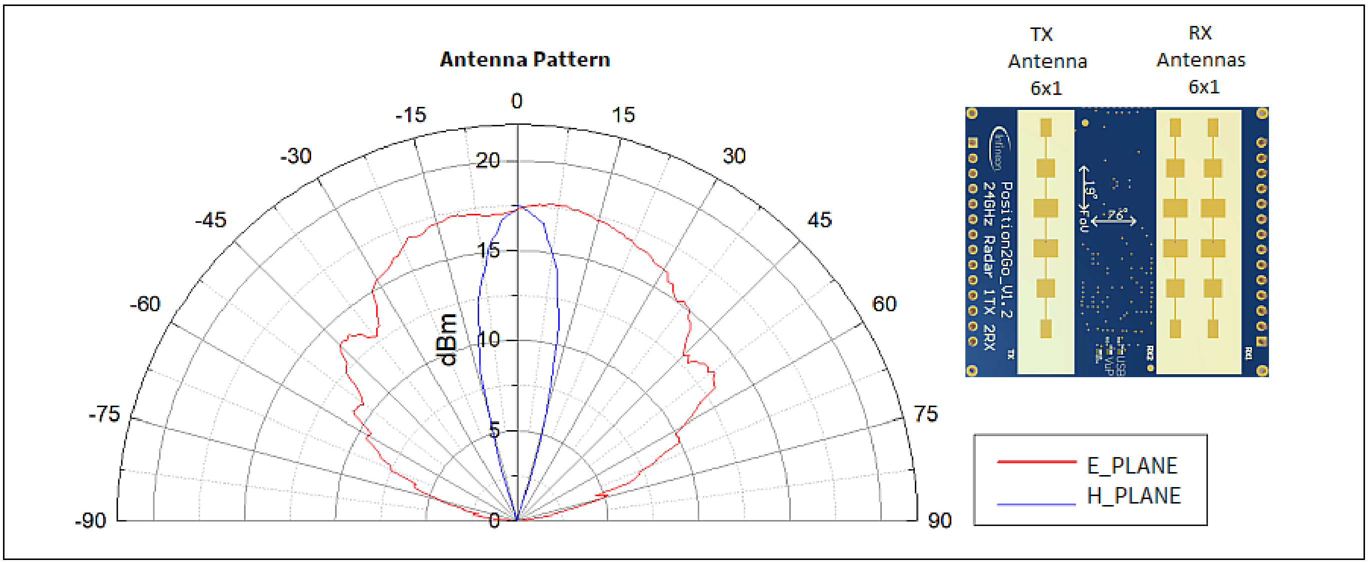


Figure 10 2D radiation pattern for array antennas

It must be noted that the values of 19 x 76 degrees are for 3 dB Half Power Beamwidth (HPBW). This implies that the gain of the antenna beyond these angles is 3 dB lower than the maximum gain at 0 degrees. In practical cases, a target with large RCS can still be detected for this reduced gain. In addition, weaker targets (i.e., low RCS) in close proximity to the radar can also be detected outside the opening angles. Therefore, a careful judgement has to be made regarding the radar detection zone by taking into account both distance of target from radar and also the target RCS.

3.5 Prescaler output and PLL section

BGT24MTR12 has two prescaler outputs: Q1 and Q2. Q1 represents the VCO output divided by a factor of 24. Q2 represents the VCO output divided by a factor of 220. As shown in Figure 11, the Q1 output is connected to the RF input terminal of a low-noise fractional-N PLL LMX2491 with integrated ramp/chirp generation functionality. The prescaler output from the MMIC is DC-coupled via capacitor C27.

The VCO can be controlled by DC inputs on two different pins: VCOARSE (Pin 6) and VFINE (Pin 5) of the BGT24MTR12. The VCOARSE and VFINE pins are tied together and connected to the PLL's charge pump output voltage (CPout) via a loop filter circuit. The loop filter has been optimized for an FMCW ramp of 300 µs. A 40 MHz reference oscillator is used as the clock source for the PLL. Table 2 lists the loop filter components with their values.

Note: Schematics with more detailed information can be downloaded from the Infineon Developer Center.

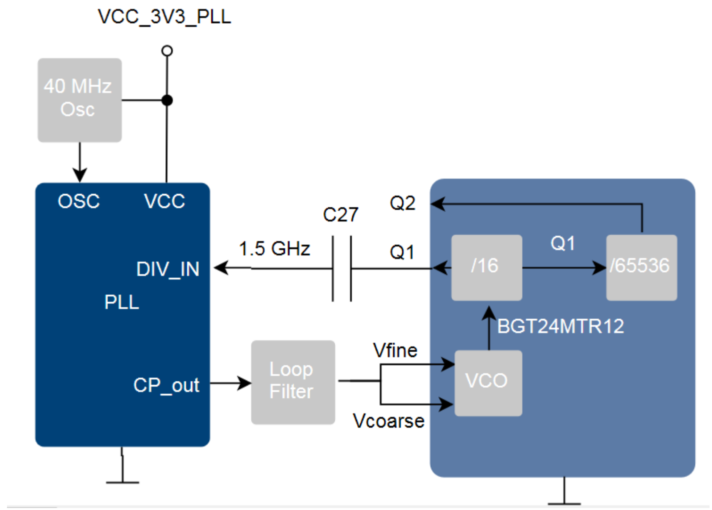


Figure 11 PLL control loop block diagram

Table 2 PLL loop filter components and values

Component	Value
C23	33 nF
C22	2.2 nF
C37, C38	150 pF
R23	820 kΩ
R25	120 Ω

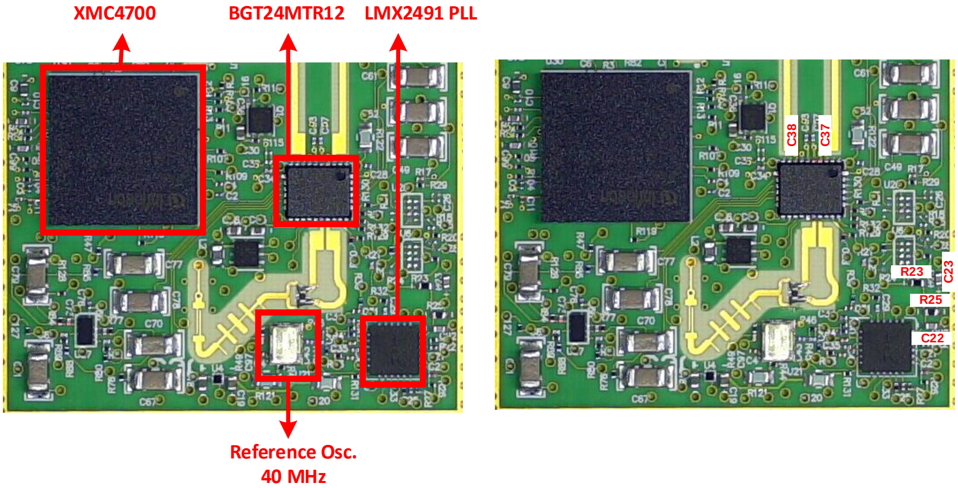
The current firmware version provided with the module is optimized and tested with sawtooth ramps of 300 µs. In principle, use of other ramp types (e.g., triangular) and other ramp durations should also be possible. However, this is not tested using the hardware/firmware configurations provided and may require reconsidering other system timing settings (e.g., duty-cycle, waiting times, etc.) and baseband section modification.

For the optimized PLL settings, refer to the delivered DAVE™ project. Apart from the SPI pins, Table 3 lists the other PLL pins accessible on the module via the MCU for various configuration settings.

Table 3 PLL pin description

Pin number – PLL	Description	Functionality	MCU pin connection
Pin 12	MOD	Multiplexed input/output pins for ramp triggers, FSK/PSK modulation, FastLock, and diagnostics	P1.2
Pin 13	CE	Chip enable	P2.2
Pin 17	MUXOUT	Multiplexed input/output pins for ramp triggers, FSK/PSK modulation, FastLock, and diagnostics	P1.0
Pin 20	TRIG 1	Multiplexed input/output pins for ramp triggers, FSK/PSK modulation, FastLock, and diagnostics	P1.3
Pin 21	TRIG 2	Multiplexed input/output pins for ramp triggers, FSK/PSK modulation, FastLock, and diagnostics	P1.1

The Q2 prescaler output from the BGT24MTR12 is 23 kHz and this is fed into the CCU4 of the XMC4700 MCU. This can be used to keep the VCO inside the ISM band by controlling the tuning voltage pins via the MCU's DAC. This procedure would eliminate the need for hardware PLL but requires complex ramp generation, linearization techniques and signal processing algorithms for proper target detection. The Position2Go demo board is designed to implement this functionality if one desires to do so. However, Infineon currently does not provide firmware, supporting such software-based ramp generation for distance measurements. When using the Q2 output, it is very important to keep the Q1 output terminated with a DC block to obtain a proper Q2 signal at the microcontroller timer input. It is recommended to keep the Q2 divider off during signal processing to prevent unwanted spurs and baseband noise.

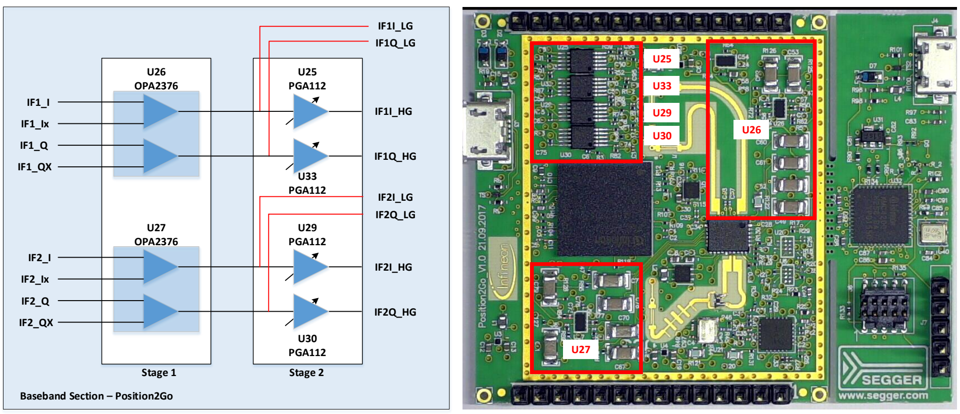


a) PLL section components b) Loop filter components

Figure 12 PLL section overview with loop filter components

3.6 Analog baseband section

The BGT24MTR12 provides both in-phase and quadrature-phase Intermediate Frequency (IF) signals from each of its receive channels. The in-phase and quadrature-phase signals are differential in nature, thus making available four different IF output signals from each receive channel (IFI, IFIx, IFQ and IFQx). Depending on the target in front of the radar antennas, the analog output signal from the BGT24MTR12 chipset can be very low in amplitude (µV to mV range). To process these low-amplitude signals it is necessary to amplify the IF signals that come out of the RF front end with analog amplifiers.



a) Baseband section concept b) Baseband components

Figure 13 Baseband amplifier chain on PCB

The Position2Go demo board enables the user to select either the low gain (first stage only) or high gain (first stage + second stage) mode depending on the target RCS and the distance to be detected by simply configuring the MCU pin settings in the software. No hardware changes are needed for this process. Table 4 lists the MCU pins associated with each of the gain stages. Use the graphical pin select tool in the DAVE™ software to select the appropriate pins for signal processing.

Table 4 Baseband amplifiers to MCU pin connections

XMC4700 – BGA196 – port pin	Pin function
P14.4	IF1I – high gain
P14.14	IF1Q – high gain
P15.3	IF2I – high gain
P15.8	IF2Q – high gain

3.6.1 Gain settings

The Position2Go demo board has a two-stage baseband amplification process. The first stage is designed with an operational amplifier with fixed gain and cut-off frequency settings. The second stage has PGAs to adjust the gains easily using SPI.

The baseband section of the Position2Go demo board is designed to have a bandpass characteristic. Due to limited isolation between the TX and RX of the radar system, there is a feed-through of the TX signal into the RX part. Consequently, there is always a dominant low-frequency component at the receiver output of the radar MMIC. The value of this low-frequency component depends on the value of the FMCW ramp settings. This low-frequency signal will be further amplified by the gain of the baseband section and may completely saturate the radar IF chain (ADCs and further amplifier stages). This effect is inherent to all FMCW radar systems and cannot be eliminated completely in the analog domain. The TX-to-RX cross-talk effect also limits the minimum distance that can be measured by the radar. However, by using appropriate filtering, the effect of this cross-talk can be minimized. This requires the implementation of filtering stages prior to the amplification of the IF signal by the baseband section.

Stage 1 is designed for a gain of 23.5 dB with a 3 dB bandwidth from 14 kHz to 140 kHz. The second IF amplifier stage consists of a programmable gain amplifier, and in combination with the first IF stage provides a total IF gain of maximum 65.5 dB with a 3 dB bandwidth from 13 kHz to 105 kHz.

Table 5 IF baseband section gain settings

Radar GUI setting	Binary gain	PGA gain (dB)	Total baseband section gain (dB)
Max.	128	42	65.5
L6	64	36	59.5
L5	32	30	53.5
L4	16	24	47.5 (default setting)
L3	8	18	41.5
L2	4	12	35.5
L1	2	6	29.5
Min.	1	0	23.5

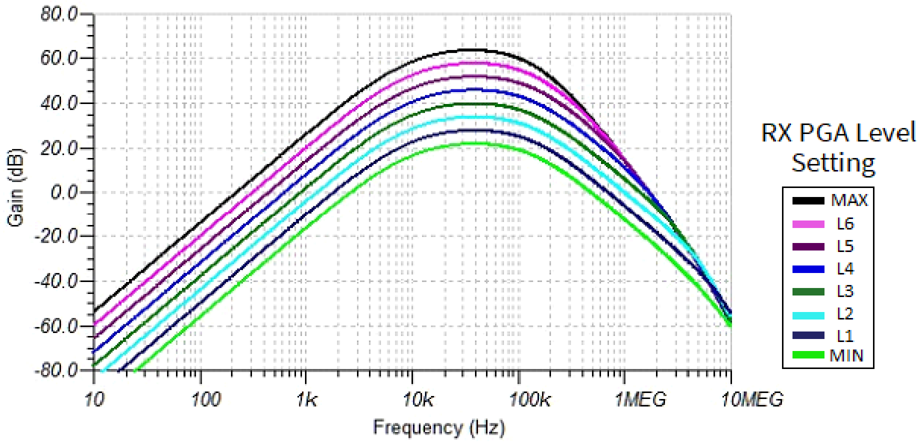


Figure 14 **PGA gain plots for different settings**

For short-range measurements (less than 10 m) it is sufficient to use only a single IF amplification stage. The PGAs can be removed for this range, thereby reducing the BOM cost. For long-range measurements (more than 10 m), and for targets with very low and varying RCS (e.g., human beings) the radar may not be able to provide a precise detection, depending on the environmental condition.

3.6.2 IF section and FMCW ramp settings

The bandpass characteristics of the IF section are also determined from the FMCW ramp parameter settings. Different ramp settings led to different IF frequencies for targets at different distances. Table 6 gives an example of IF frequencies produced by stationary targets at particular distances corresponding to different sawtooth-type ramp parameters. These IF frequencies are also called as "beat frequencies". The beat frequencies calculated in Table 6 do not include the Doppler shift. The $Beat\ Frequency\ (Fb)$ is calculated from the following formula:

$$Beat\ Frequency\ (Fb) = \frac{2 * \mathrm{R} * \Delta\mathrm{f}}{\mathrm{c} * T_r}$$

Where R = target distance in meter (m)

Δf = ramp bandwidth in Hertz (Hz)

T_r = ramp time in second (s)

c = speed of light in meter/second (m/s)

Table 6 **IF frequency vs. FMCW ramp parameters vs. target distance**

Ramp duration (µs)	Ramp bandwidth (MHz)	Beat frequency (kHz)			
		Target at 0.5 m	Target at 5 m	Target at 10 m	Target at 25 m
300	180	2	20	40	100
300	200	2	22	44	111
400	180	2	15	30	75
400	200	2	17	33	83
500	180	1	12	24	60
500	200	1	13	27	67

3.7 Duty-cycle circuit for low-power operation (default mode)

The Position2Go demo board offers the possibility of operating the BGT24MTR12 and PLL in a duty-cycle mode. This is done by enabling/disabling the PMOS (Q1) over the pin P2.3 of the MCU, as shown in Figure 15. Toggling this pin enables switching the power supply on/off to the MMIC over the FET. The signal is low-active and has a pull-down resistor in place. The PLL is switched on/off using the CE pin. In its default state, the module is already programmed for the duty-cycle mode of operation.

To enable the operation of BGT24MTR12, the trigger pin of LDO U23 connected to the MCU port pin P4.3 must be configured first. This is already implemented in the default software. Care must be taken when changing anything on the firmware, and it must be ensured that the LDO U23 is enabled via the MCU pin P4.3.

It is recommended to use the module in a duty-cycle mode to keep the overall power consumption and thermal dissipation low. Position2Go was designed to have a compact form factor. Keeping the BGT24MTR12 always turned on will heat up the module significantly and could result in undefined behavior. In such cases it is recommended to turn off all the unused building blocks inside the BGT24 via the SPI, and for short distance measurements reduce the transmit output power to minimum. Also putting the microcontroller in a deep sleep mode when it is not in operation will help to minimize power consumption and thermal dissipation significantly. The current firmware does not include the settings to put the microcontroller in a power-optimized mode.

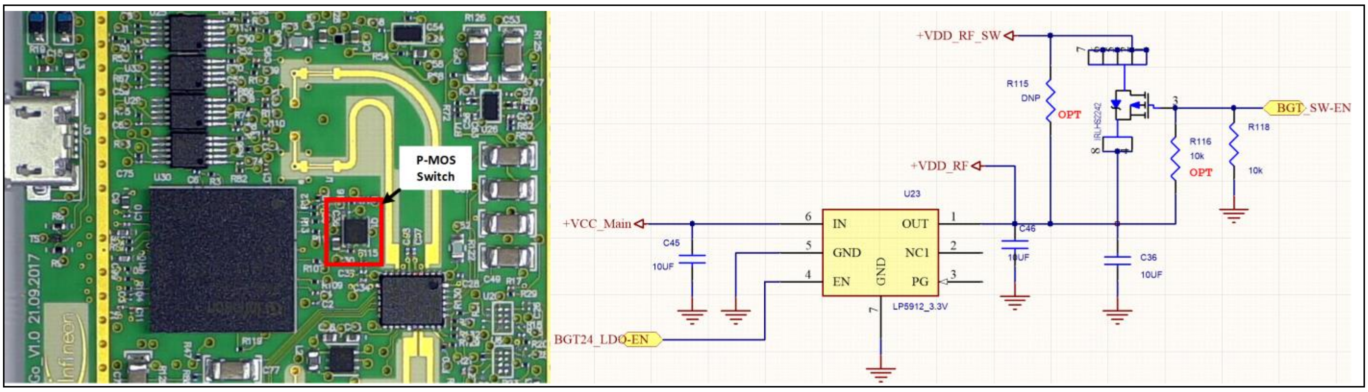


Figure 15 BGT24MTR12 duty-cycle concept

The module also offers a second possibility to turn off the BGT24MTR12 and the IF section by using the LDO trigger pins. The BGT24MTR12 and the baseband stage 1 consisting of U26 and U27 can be turned off by disabling the LDO U23. This will also turn off the reference voltage generator IC U24. The PGAs can be turned OFF by disabling the LDO U28 via pin P7.11 of the MCU. It must be noted that this mode requires detailed timing analysis for proper signal processing, due to slower start-up time of the LDO and baseband amplifiers when compared to the PMOS. The reduction in power consumption is minimal, since the baseband amplifiers consume very low power. The IF section is not duty-cycled in the default board configuration.

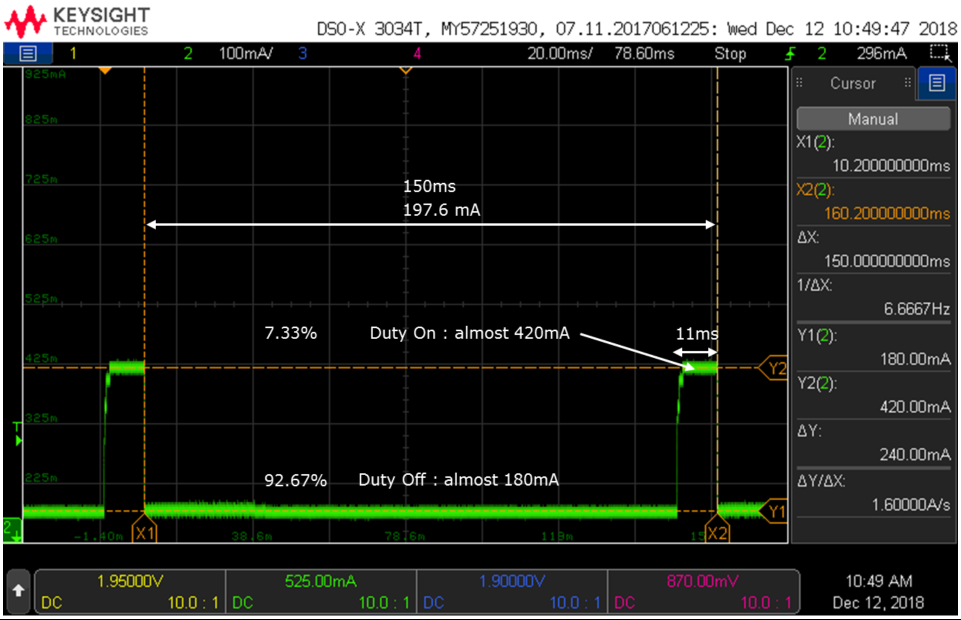


Figure 16 Duty-cycle vs. no duty-cycle current consumption

As shown in Figure 16, during duty-cycle on-time the demo board typically draws 420 mA, while during the duty-cycle off-time with deactivated BGT24MTR12 and PLL, only 180 mA. With the default configuration of 7.3 percent on-time the demo board has a typical average current consumption of 200 mA.

3.8 External pin header connectors

The Position2Go demo board has the provision to connect two 14-pin headers on the edges of the board as shown in Figure 17. These pins are described in Table 7.

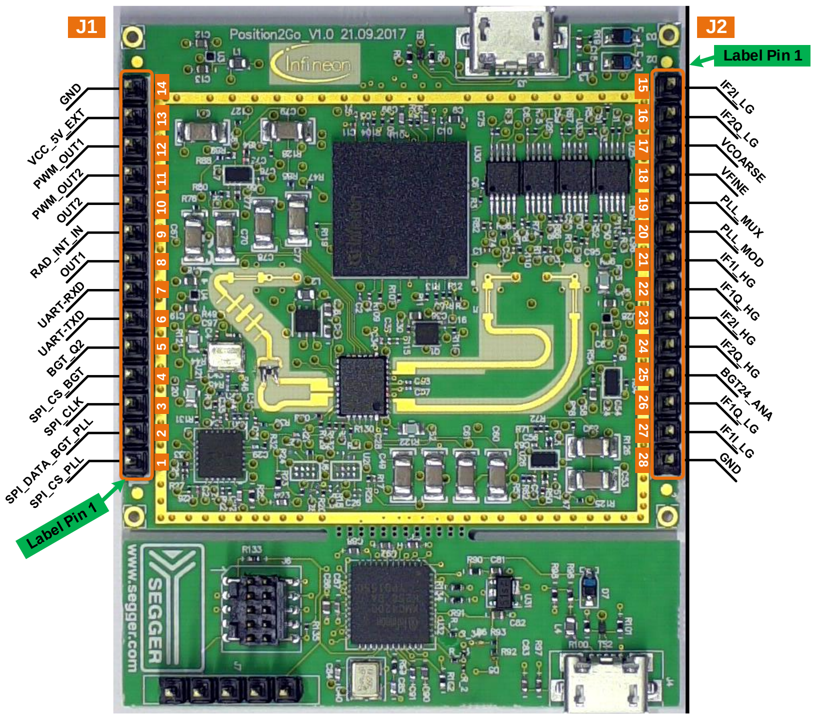


Figure 17 Position2Go external header pin overview

Table 7 External headers – pin description

Pin no.	Signal name	Pin description
1	SPI_CS_PLL	SPI chip select input/output – LMX2491 PLL
2	SPI_DATA_BGT_PLL	SPI master out slave input/output (BGT and PLL)
3	SPI_CLK	SPI clock input/output
4	SPI_CS_BGT	SPI chip select input/output – BGT24MTR12
5	BGT_Q2	BGT24MTR12 Q2 prescaler output – 23kHz
6	UART-TXD	Transmit pin for UART communication
7	UART-RXD	Receive pin for UART communication
8	OUT1	External GPIO pin (user-configurable)
9	RAD_INT_IN	GPIO pin for interrupt signals (user-configurable)
10	OUT2	External GPIO pin (user-configurable)
11	PWM_OUT2	External GPIO with CCU4 unit (user-configurable)
12	PWM_OUT1	External GPIO with CCU4 unit (user-configurable)
13	VCC_5V_EXT	External +5.0 V input power supply pin (maximum = 5.5 V)
14	GND	Ground
15	IF2I_LG	BGT24MTR12 RX-2 I-channel – analog signal output – first gain stage
16	IF2Q_LG	BGT24MTR12 RX-2 Q-channel – analog signal output – first gain stage
17	VCOARSE	BGT24MTR12 – VCO coarse tuning input (0.5 to 3.3 V)
18	VFINE	BGT24MTR12 – VCO fine tuning input (0.5 to 3.3 V)
19	PLL_MUX	Multiplexed input/output pins for ramp triggers, FSK/PSK modulation, FastLock and diagnostics
20	PLL_MOD	Multiplexed input/output pins for ramp triggers, FSK/PSK modulation, FastLock and diagnostics
21	IF1I_HG	BGT24MTR12 RX-1 I-channel – analog signal output – second gain stage
22	IF1Q_HG	BGT24MTR12 RX-1 Q-channel – analog signal output – second gain stage
23	IF2I_HG	BGT24MTR12 RX-2 I-channel – analog signal output – second gain stage
24	IF2Q_HG	BGT24MTR12 RX-2 Q-channel – analog signal output – second gain stage
25	BGT24_ANA	Multiplexed output pins of BGT24MTR12 to read various sensor values
26	IF1Q_LG	BGT24MTR12 RX-1 Q-channel – analog signal output – first gain stage
27	IF1I_LG	BGT24MTR12 RX-1 I-channel – analog signal output – first gain stage
28	GND	Ground

The pin headers enhance the functionality of the module significantly. They allow probing the analog outputs of the sensor module and also probing various other signals provided to the IC. In principle, the accessibility of several pins on the radar MMIC and the IF signals available via the external pin headers enable interfacing the module with an external signal processor. Apart from the onboard user LEDs, the external headers provide two additional user-configurable GPIO pins from the microcontroller with a number of features and can be used to drive external shields such as the Infineon RGB LED lighting shield.

3.9 Microcontroller unit – XMC4700

The Position2Go demo board uses an XMC4700 32-bit Arm® Cortex®-M4 MCU to perform the radar signal processing. The XMC4700 takes care of communication with all the subsystems on the radar module, enables data acquisition, performs the complete radar signal processing (including sampling and FFT) and communicates the results via its UART or USB interface to an external device.

An XMC4700 in a 194-pin BGA package is used, featuring a 144 MHz CPU frequency, 2048 kB Flash and 352 kB RAM. Four 12-bit ADCs help to implement the radar signal sampling and acquire the various sensor data from the BGT24MTR12 MMIC. The MCU has also a USB 2.0 device interface which enables communication with a PC directly. Figure 18 shows a system block diagram of the XMC4000 series MCUs.

Please refer to [2] for detailed information on the XMC4700 microcontroller.

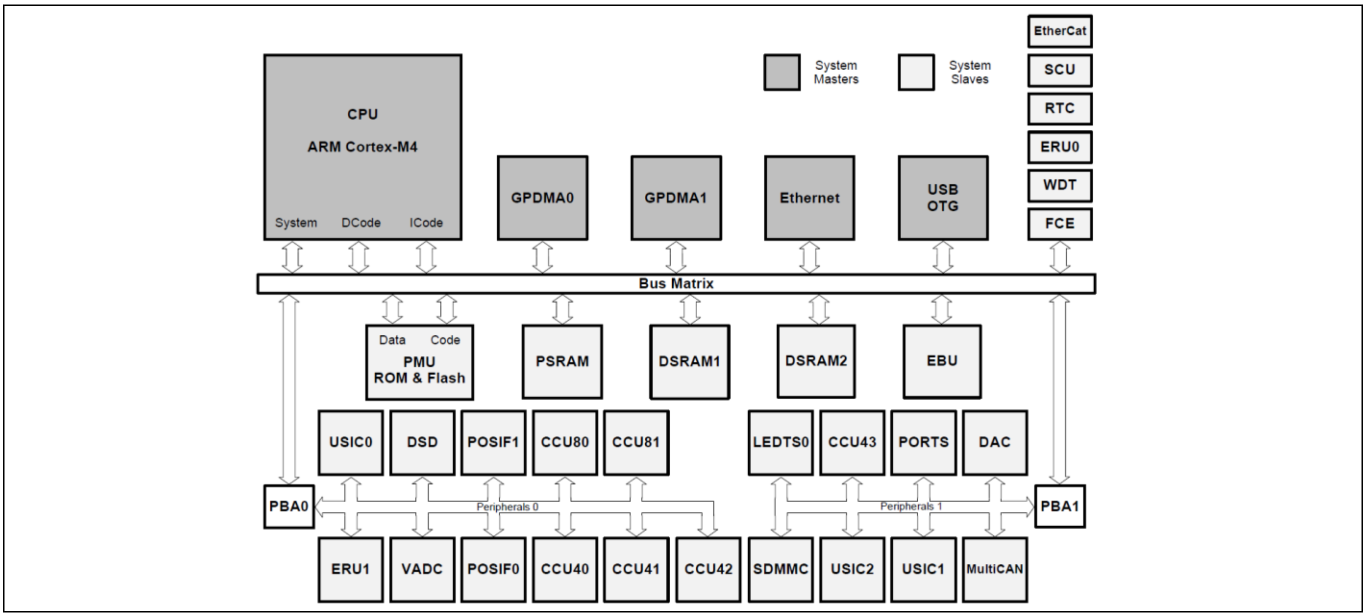


Figure 18 XMC4700 block diagram

3.10 Onboard debugger and UART connection

The onboard breakable debugger supports two-pin SWD and UART communication. Both require the installation of SEGGER's J-Link driver which is part of the DAVE™ installation.

During installation of the J-Link driver make sure to select the option "Install USB Driver for J-Link-OB with CDC" as shown in Figure 19.

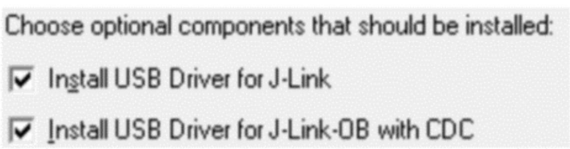


Figure 19 Recommended installation options for the J-Link driver

Table 8 shows the pin assignment of the XMC4200-VQFN48 MCU used for debugging and UART connection.

Table 8 XMC4200 pins used for debugging and UART communication

Port pin	Pin function
TMS (Pin 35)	Data pin for debugging via SWD/SPD
TCK (Pin 39)	Clock pin for debugging via SWD
0.5	Transmit pin for UART communication
0.4	Receive pin for UART communication

The debugger section supports communication between a PC/laptop and target XMC™ device via a UART-to-USB bridge). Therefore, the UART pins of the target XMC4200 on the radar main board are connected to the TX/RX pins of the debug connector. The TX pin of the debugger MCU is connected to the RX pin of the target XMC4200 MCU. The RX pin of the debugger is connected to the TX pin of the XMC™ target device.

The connectors J6 (Cortex-10 pin) and J7 (5-pin header) shown in Figure 20 are used for internal development and testing purposes and are not recommended for customer use.

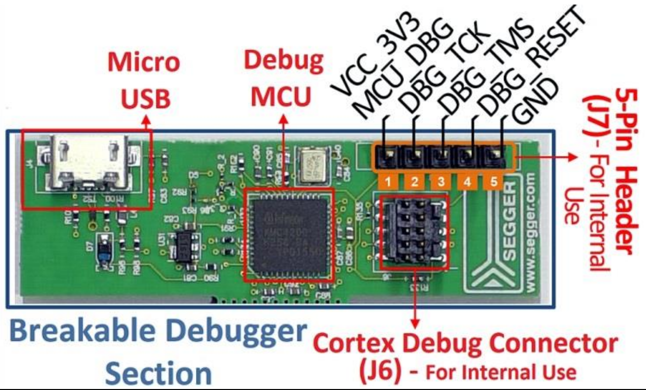


Figure 20 Breakable onboard debugger section

3.11 User LEDs

Some pins of the XMC4700 on the Position2Go demo board are connected to external LEDs on the antenna side of the PCB for status indication. Table 9 lists the user LEDs pin assignment.

Table 9 User LEDs pin assignment

LED	MCU port pin
D8 (green LED)	P7.8 (H14)

4 Measurement results

4.1 Measurement default configuration

The Position2Go demo board was used in the default configuration for distance and angle measurements:

- BW: 200 MHz
- Chirp time: 300 µs
- TX power level: 7
- RX PGA level: L4
- RX BGT LNA gain: enabled
- Duty-cycle status: enabled

4.2 Maximum distance measurement

The maximum distance was measured with a defined detection range threshold of 100 LSB in an outdoor scenario with minimum environmental clutter. Higher detection ranges can be achieved with larger RCS targets and by increasing the RX PGA level.

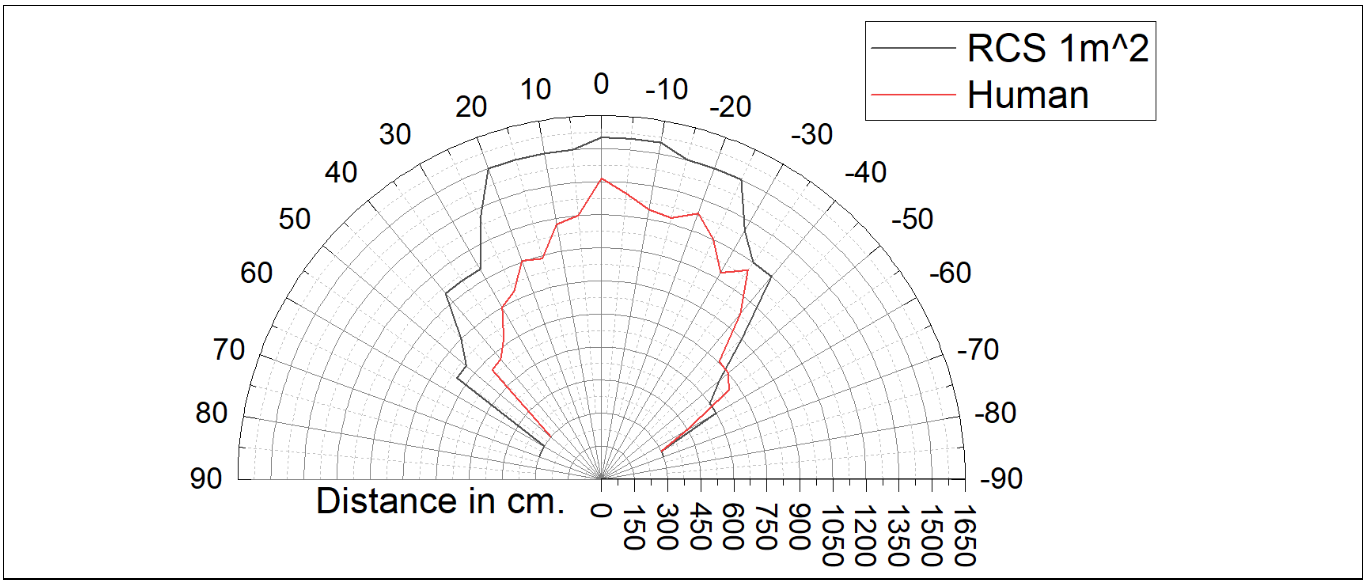


Figure 21 **Maximum distance measurement vs. AoA**

Note: *For indoor measurements, like with all FMCW radar, the maximum detection range of human targets will reduce significantly. It is challenging to quantify the maximum detection range in such indoor measurement cases reliably due to unknown levels of background clutter specific to each environment.*

4.3 Range accuracy measurement

Figure 22 shows the set-up of the radar module for range measurements and the range accuracy plots for the measurements.

As can be seen from the measurement plots, the target could be measured up to 18 m away with an accuracy of ±15 cm up to 13 m and accuracy of ±25 cm for the 13 to 18 m range.

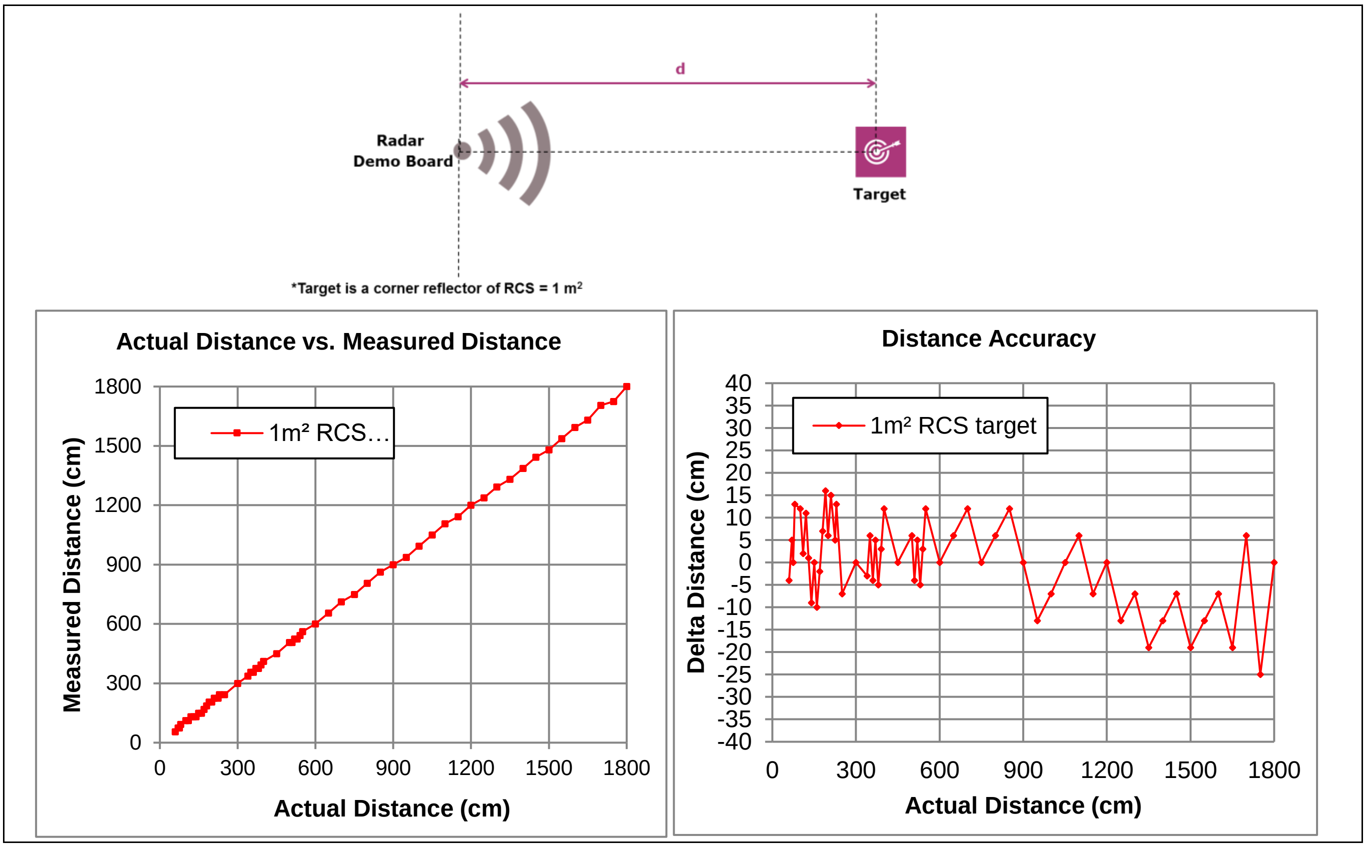


Figure 22 Range accuracy for 1 m² corner reflector target

4.4 Angular accuracy measurement

Figure 23 shows the set-up of the radar module for range measurements and the angular accuracy plots for the measurements. The demo board was used in the default configuration (as mentioned in Section 4.1). For accurate angle measurements it is necessary to avoid signal clipping in the IF baseband section.

The measurement was performed in an outdoor environment at 3 m distance with an RCS target of 1 m². As can be seen from the results, the angular accuracy was ±2 degrees in the ±20 degrees angular range and ±8 degrees in the ±65 degrees angular range.

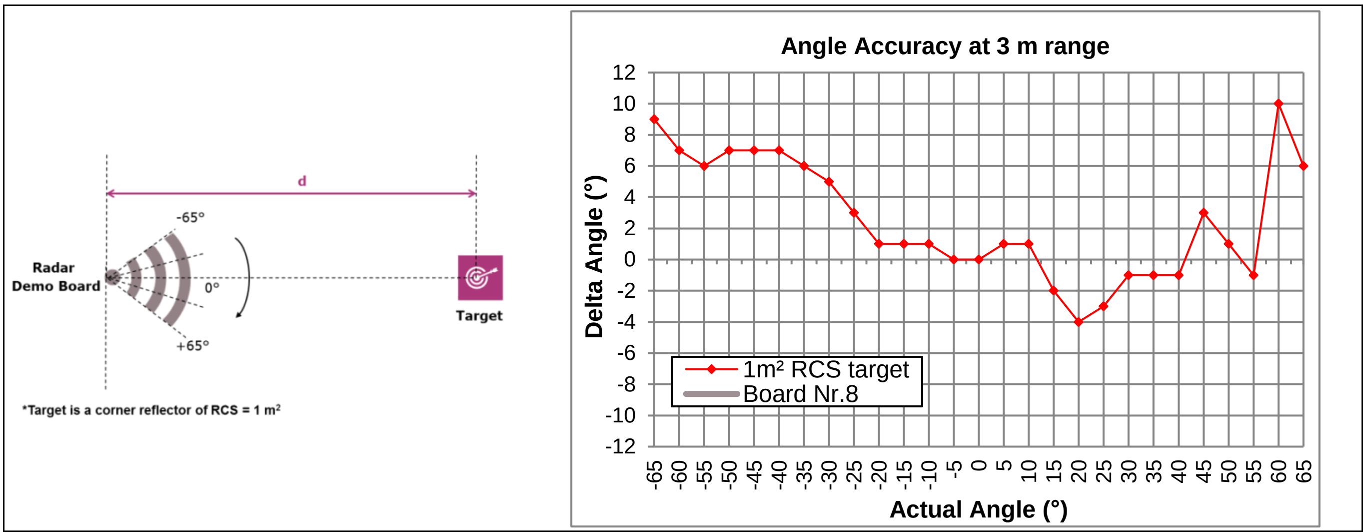


Figure 23 Angular accuracy for 1 m² corner reflector target

4.5 Temperature chamber measurement

Three temperature chamber measurements were performed for 25°C, 85°C and -35°C. Figure 24, Figure 25 and Figure 26 show the results and verify that the Position2Go demo board remains within the designated ISM band at these temperatures.

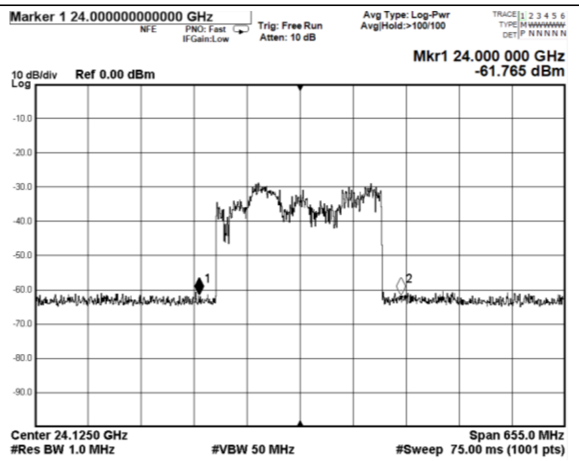


Figure 24 Temperature measurement at 25°C (markers at 24.000 GHz and 24.250 GHz)

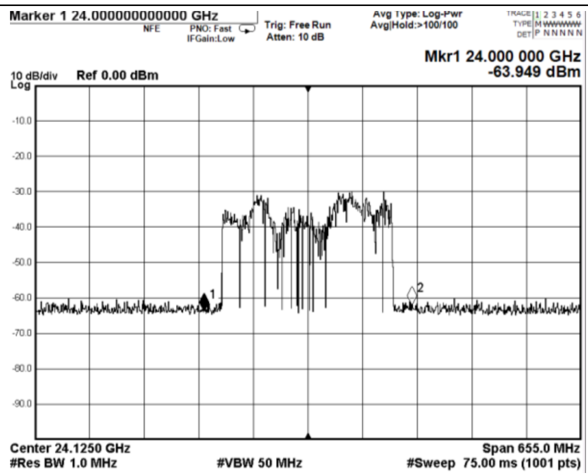


Figure 25 Temperature measurement at 85°C (markers at 24.000 GHz and 24.250 GHz)

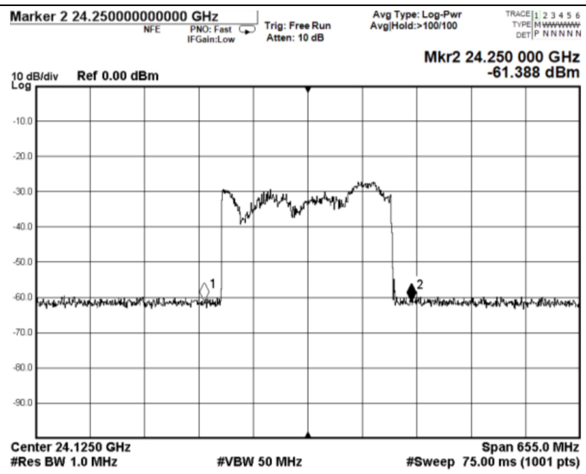


Figure 26 Temperature measurement at -35°C (markers at 24.000 GHz and 24.250 GHz)

5 Frequency band and regulations

5.1 24 GHz regulations

Infineon's BGT24MTR12 radar sensor operates in the globally available 24 GHz bands. There is an Industrial, Scientific, and Medical (ISM) band from 24 to 24.25 GHz. However, each country may have deviating regulations in terms of occupied bandwidth, maximum allowed radiated power, conducted power, spurious emissions, etc. Therefore, it is highly recommended checking the local regulations before designing an end product.

5.2 Regulations in Europe

In Europe, the European Telecommunications Standards Institute (ETSI) defines the regulations. For more details on the ETSI standards, please refer to the document EN 300 440 V2.2.1. Please note that some countries do not follow harmonized European standards. Thus, it is recommended to check national regulations for operation within specific regions and monitor regulatory changes.

5.3 Regulations in the United States of America

In the USA, the Federal Communications Commission (FCC) defines standards and regulations. The ISM band covers 24 to 24.25 GHz and one can operate field disturbance sensors anywhere within this band within allowed power limits for certain applications. For details, please refer to FCC section number 15.245 or 15.249.

References

[1] Infineon Technologies AG. BGT24MTR12 MMIC Datasheet

[2] Infineon Technologies AG. XMC4700 32-bit Arm® Cortex®-M4 microcontroller Datasheet

[3] Infineon Technologies AG. AN305: User's guide to BGT24MTR11

[4] InnoSenT GmbH (2018, 12) Application Note IV. Recommendations for the using of radar sensors in general and specifically for low cost devices

[5] InnoSenT GmbH (2018, 12) Application Note II. Detection and ranging of moving and stationary objects by using the FMCW radar principle

[6] ETSI regulations. EN 300 440 V2.2.1

[7] FCC regulations. 15.245, 15.249

Revision history

Document revision	Date	Description of changes
1.00	2018-12-14	Initial version
1.10	2019-06-14	p. 33: Added temperature chamber measurements p. 35: Added frequency regulation information Removed Firmware description, Programming API, Algorithm description and GUI overview sections
1.20	2019-09-16	p. 10: Added Minimum speed row to the System performance table
1.30	2020-05-05	p. 10: Corrected minimum and maximum speed values and formula
1.40	2023-02-14	Miscellaneous document cleanup updates

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